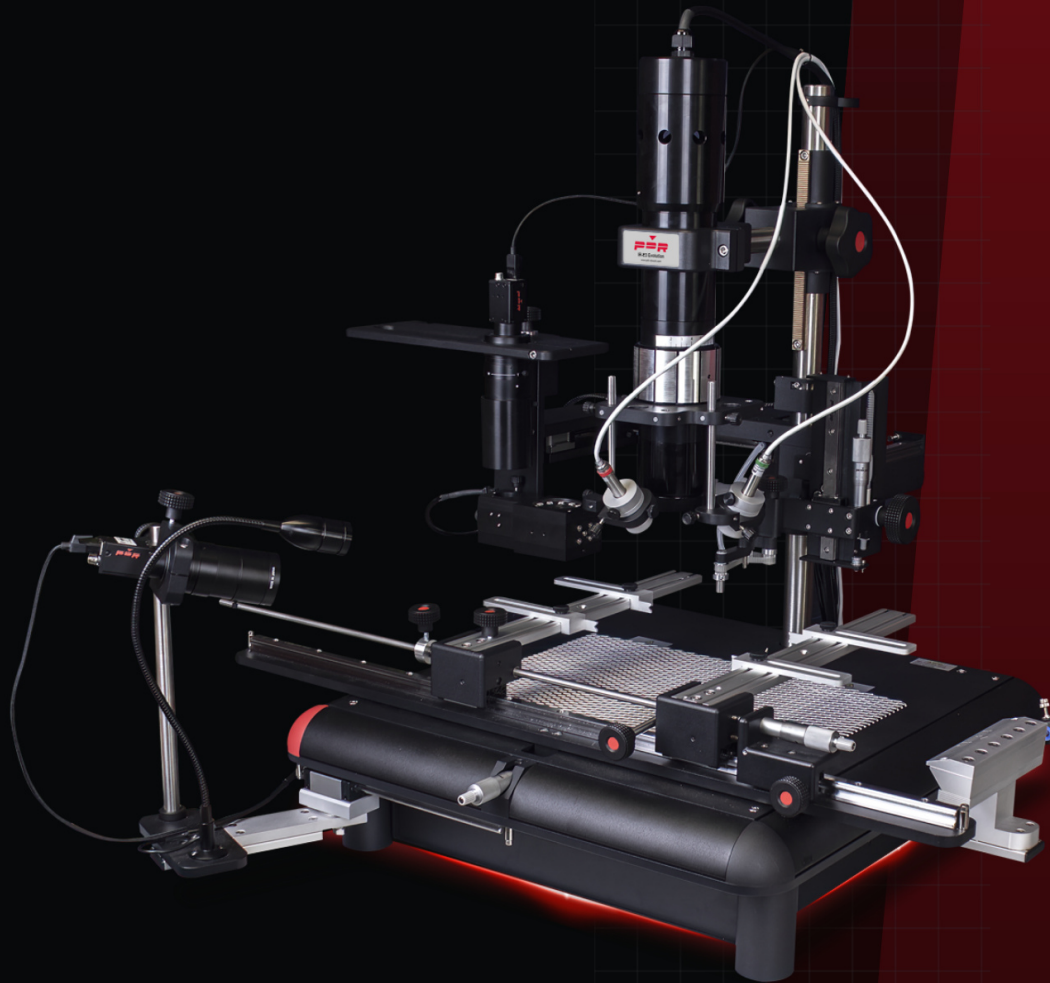


PDR FORENSICS

CHIPMATE AUTO. CONTROLLED CHIP-OFF.

Forensic laboratory system with non-contact sensing, evidence capture and precision placement.



STANDARDISE THE MOVEMENT.

Temperature-controlled Focused IR. Stored thermal profiles. Designed for forensic laboratories.

WHY AUTOMATE?

STANDARDISE THE MOVEMENT.

Standardise the movement after full solder reflow. Chipmate Auto keeps the controlled thermal process and automates the removal and placement movement.

01 AUTOMATIC REMOVAL

Once full solder reflow is achieved, the system performs the programmed removal movement.

WHY IT MATTERS

Reduces variation caused by manual lift-off.

02 AUTOMATIC PLACEMENT

Pickup and placement can be repeated as a defined machine movement.

WHY IT MATTERS

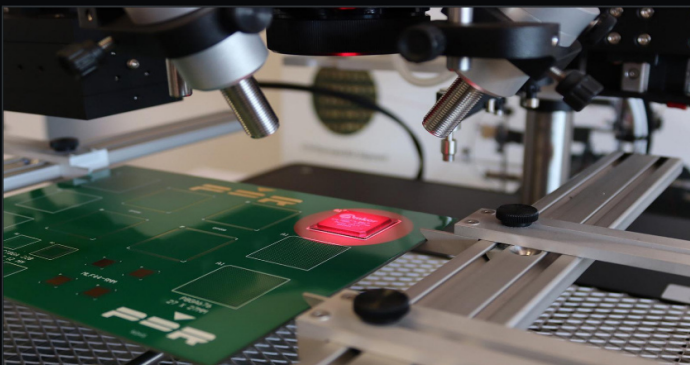
Improves consistency where the same procedure is performed repeatedly.

03 NON-CONTACT SENSING + PROFILES

Component and PCB are tracked independently and proven settings can be stored.

WHY IT MATTERS

Combines thermal repeatability with repeatable movement.



FOCUSED INFRARED | TARGETED COMPONENT HEATING

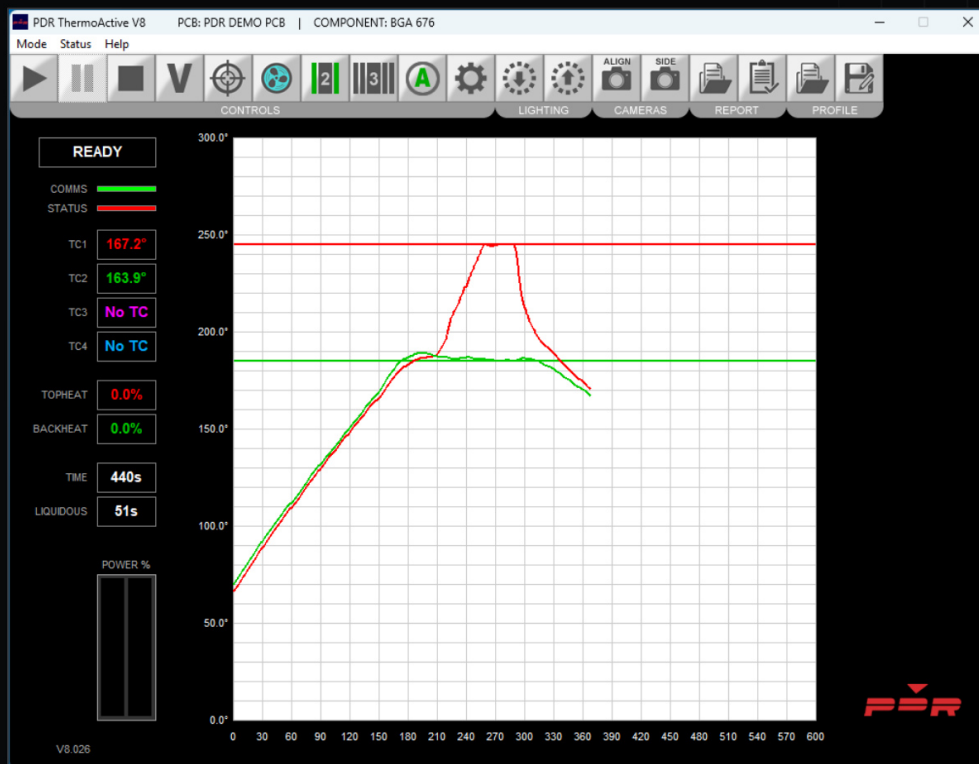


AUTOMATED REMOVAL + PLACEMENT

THERMOACTIVE PROCESS CONTROL

THERMAL CONTROL DRIVES AUTOMATION.

The thermal profile is controlled first. Once the defined process condition is reached and full solder reflow is achieved, Chipmate Auto performs the programmed removal or placement movement.



FULL THERMOACTIVE INTERFACE

RED = COMPONENT · GREEN = PCB

NON-CONTACT TEMPERATURE SENSING

Component and PCB remain separate thermal targets.

STORED THERMAL PROFILES

Repeat the same controlled process on future procedures.

AUTOMATED COMPONENT REMOVAL

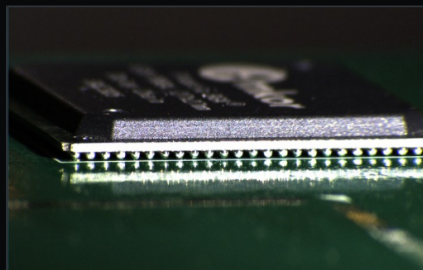
Programmed lift-off follows the controlled thermal process.

AUTOMATED PLACEMENT

Repeat placement movement with reduced operator variation.



FOCUSED INFRARED | TARGETED COMPONENT HEATING



PROCESS EVIDENCE + REPORTING



MACHINE + CORE SPECIFICATION

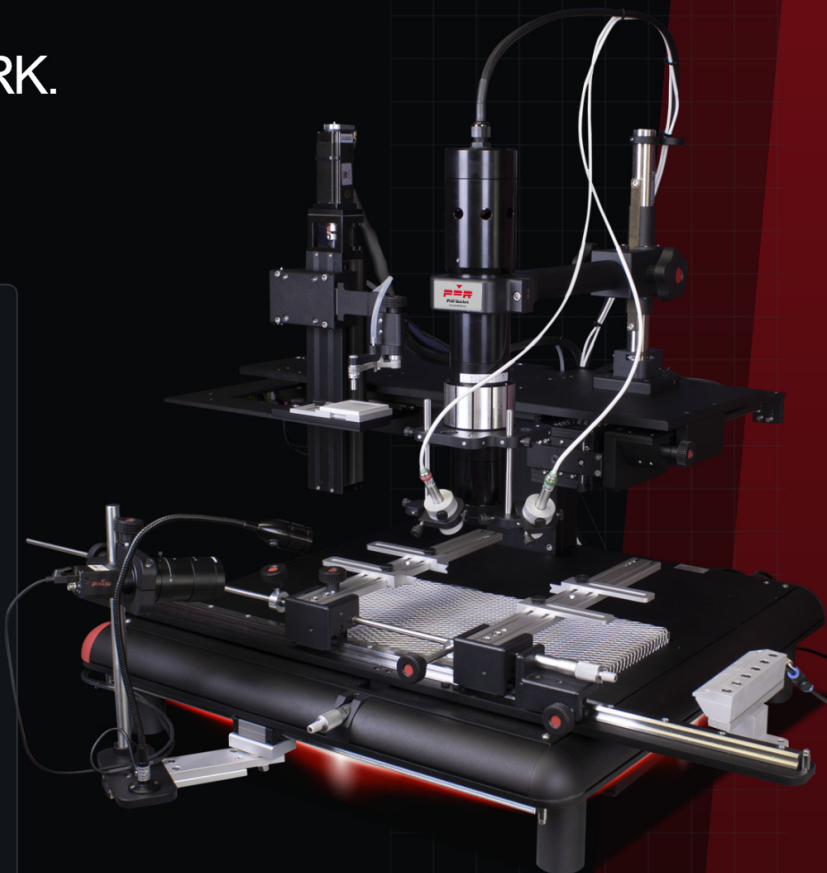
CHIPMATE AUTO. SEE IT ON YOUR CASEWORK.

CORE SPECIFICATION

MAX PCB	300 x 450 mm
MAX COMPONENT	55 x 55 mm
MIN COMPONENT	1 x 1 mm
TOP HEATER	150W focused IR, Ø70 mm
SENSING	Non-contact IR, component + PCB
REMOVAL	Automatic removal
PLACEMENT	Automatic + split-beam prism
ACCURACY	Up to 10 µm
SIDE-VIEW	Camera with image capture
SOFTWARE	ThermoActive

PDR FORENSICS

Designed and manufactured in the United Kingdom. Precision infrared since 1985. More than 5,000 PDR systems supplied worldwide.



NEXT STEP

ARRANGE A DEMONSTRATION

See the system operate on representative devices and boards from your own workflow.

SALES@PDR-FORENSICS.COM

COMPONENT CAPABILITY

BUILT FOR CRITICAL COMPONENT RECOVERY.

Controlled Focused IR supports repeatable removal across the component types commonly encountered in forensic laboratory workflows.

COMPONENTS WE SAFELY REMOVE



eMMC / eMCP
EMBEDDED MEMORY



NAND FLASH
RAW FLASH MEMORY



UFS
HIGH-SPEED STORAGE



CPU / SoC
PROCESSING DEVICES



POWER IC
POWER DEVICES



PMIC
POWER MANAGEMENT

TRUSTED BY



POLICE FORCES



FORENSIC
LABORATORIES



GOVERNMENT
AGENCIES



DATA RECOVERY
SPECIALISTS



AIR ACCIDENT
INVESTIGATION

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